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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Masakazu SATO et al.

Group Art Unit: 2863

Application No.: 10/517,655

Examiner: Brian BUI

Filed: December 13, 2004

Docket No.: 122035

For: METHOD OF EVALUATING SHAPE OF SEMICONDUCTOR WAFER AND
APPARATUS FOR EVALUATING SHAPE OF SEMICONDUCTOR WAFER

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Pursuant to 37 CFR §1.56, the attention of the Patent and Trademark Office is hereby directed to the references listed on the attached PTO-1449. Unless otherwise indicated herein, one copy of each reference is attached. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the references be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

- ☒ 1. This Information Disclosure Statement is being filed more than three months after the U.S. filing date and after the mailing date of a Final Rejection, Notice of Allowance, or other action that closes prosecution (e.g., Quayle Action), but before payment of the Issue Fee. Attached is our Check No. 189292 in the amount of \$180.00 in payment of the fee under 37 CFR §1.17(p). Please credit or debit Deposit Account No. 15-0461 as needed to ensure consideration of the disclosed information. Two duplicate copies of this paper are attached.
- ☒ a. I hereby certify that each item of information contained in this Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement.
37 CFR §1.97(e)(1).
- ☒ 2. Each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart application, and this communication was not received by any individual designated in §1.56(c) more than thirty days prior to the filing of this Information Disclosure Statement.

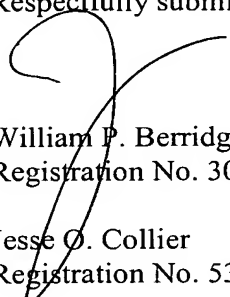
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- ☒ 3. An English language Abstract of one or more non-English language reference is attached hereto. See References 1-5.
- ☒ 4. A computer-generated English language translation of one or more Japanese Patent Publication cited herein has been obtained from the website of the Japanese Patent Office (<http://www.jpo.go.jp>), and is attached, but has not been reviewed for accuracy. See References 1, 2, 4 and 5.

Respectfully submitted,



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WPB:LXF/tjx

Date: February 9, 2007

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Sheet 1 of 1

Form PTO-1449 (REV. 1/06)		US Dept. of Commerce PATENT & TRADEMARK OFFICE		ATTY DOCKET NO. 122035		APPLICATION NO. 10/517,655	
INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary)				APPLICANTS Masakazu SATO et al.			
				FILING DATE December 13, 2004		GROUP 2863	
U.S. PATENT DOCUMENTS							
Examiner Initials	Cite No.	Document Number	Date	Name			
FOREIGN PATENT DOCUMENTS							
Examiner Initials	Cite No.	Document Number	Date	Country	With English Abstract	With English Translation	
	1.	JP A 06-034362	02/08/1994	JAPAN	X	X	
	2.	JP A 2002-039745	02/06/2002	JAPAN	X	X	
	3.	WO 02/41380 A1	05/23/2002	WIPO	X		
	4.	JP A 2000-146569	05/26/2000	JAPAN	X	X	
	5.	JP A 05-141949	06/08/1993	JAPAN	X	X	
OTHER DOCUMENTS							
Examiner Initials	Cite No.	(Including Author, Title, Date, Pertinent Pages, etc.)					
EXAMINER					DATE CONSIDERED		
Examiner: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

Date: February 9, 2007